



Material Content Data Sheet



Sales Product Name		BSZ0909ND		Issued		24. January 2018		
MA#		MA001645492						
Package		PG-WISON-8-1		Weight*		23.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.007	0.03		319	
	noble metal	gold	7440-57-5	0.028	0.12		1235	
	inorganic material	silicon	7440-21-3	0.149	0.65	0.80	6461	8015
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		125	
	non noble metal	zinc	7440-66-6	0.012	0.05		500	
	non noble metal	iron	7439-89-6	0.230	1.00		10007	
	non noble metal	copper	7440-50-8	9.354	40.63	41.69	406320	416952
wire	non noble metal	copper	7440-50-8	0.224	0.97	0.97	9736	9736
encapsulation	organic material	carbon black	1333-86-4	0.025	0.11		1093	
	plastics	epoxy resin	-	1.296	5.63		56274	
	inorganic material	silicondioxide	60676-86-0	11.258	48.91	54.65	488982	546349
leadfinish	non noble metal	tin	7440-31-5	0.360	1.56	1.56	15645	15645
plating	noble metal	silver	7440-22-4	0.076	0.33	0.33	3303	3303
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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